

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HSU227

Silicon Schottky Barrier Diode for High Speed Switching



ADE-208-779A (Z)

Rev. 6
Aug. 2000

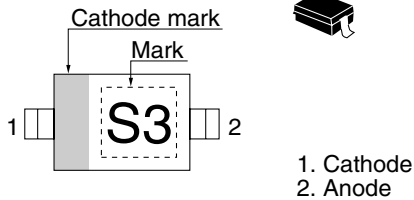
Features

- Low capacitance. (C = 3.0 pF max)
- Ultra small Resin Package (URP) is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSU227	S3	URP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	25	V
Average rectified current	I_o	50	mA
Non-Repetitive peak forward surge current	I_{FSM}^*	200	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note: 10msec sine wave 1 pulse

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	0.29	0.35	V	$I_F = 1 \text{ mA}$
Reverse current	I_R	—	0.3	2.0	μA	$V_R = 20 \text{ V}$
Capacitance	C	—	2.45	3.0	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$

Main Characteristic

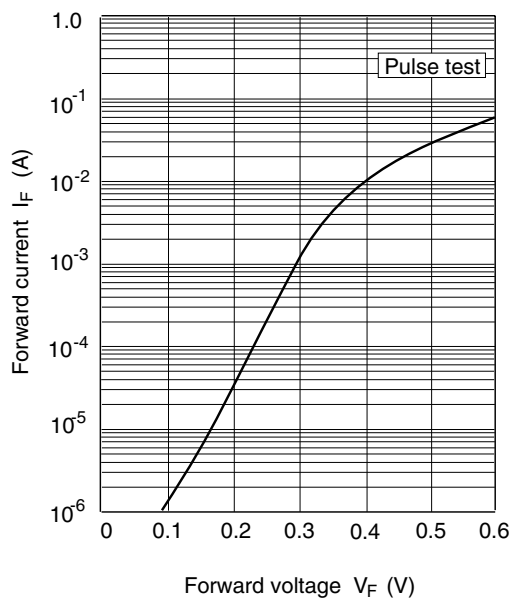


Fig.1 Forward current Vs. Forward voltage

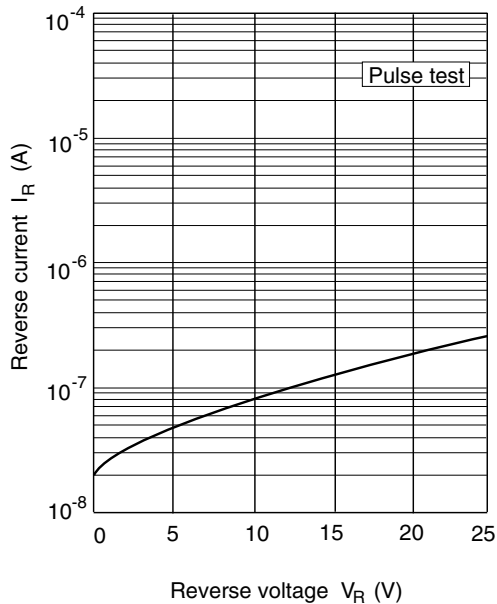


Fig.2 Reverse current Vs. Reverse voltage

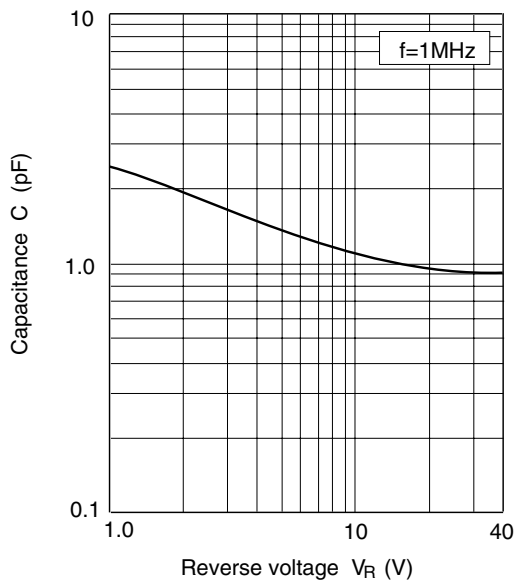
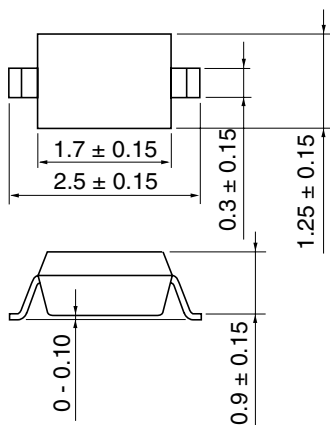


Fig.3 Capacitance Vs. Reverse voltage

Package Dimensions

Unit: mm



Hitachi Code	URP
JEDEC	—
EIAJ	—
Mass (reference value)	0.004 g

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Colophon 4.0



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